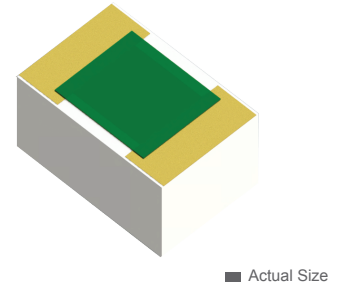


RM0805ZZ-XXXXWN-99 Features:

- Single-Sided Terminals w/ Backplane Configuration
- Solder, Epoxy or Wirebondable Terminals
- Solder or Epoxy Mount Backplane
- Customer Defined Testing Available
- RoHS Compliant or SnPb Available
- Non-Magnetic Available
- Tape & Reel and Waffle Pack Available (Standard is bulk)

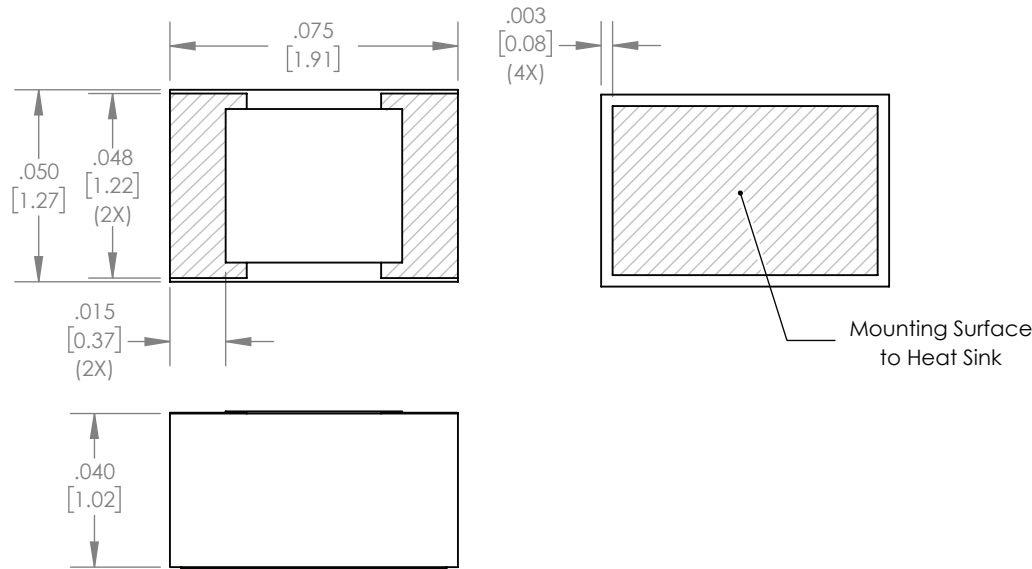


RM0805ZZ-XXXXWN-99 Parameters:

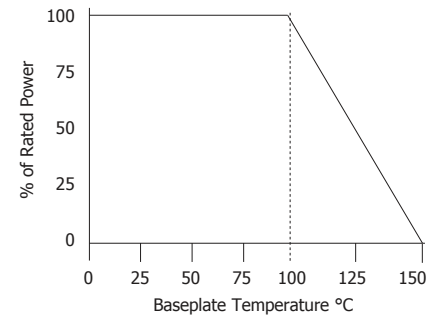
Resistance Range: 0.5Ω - 1MΩ
 Rated Power:* 5W
 Construction: Thick Film on 0.040" BeO
 Operating Temperature: -55 to +150°C

* Rating based on ≤100°C constant baseplate temperature

RM0805ZZ-XXXXWN-99 Dimensions:



RM0805ZZ-XXXXWN-99 Power Derating Curve



Dimensions in inches [mm]
 Tolerance is ± 0.005 [0.13]
 unless otherwise stated

Ordering Information:

Example Part Number: RM0805CT-50R0JN-99

RM	0805	ZZ	-	XXXX	W	N	-	99	UU	
Prefix for Resistor w/ Single-Sided Terminals and Backplane		Value Code		Tolerance		Normal Inspection Contact factory for additional options	Substrate		Packaging	
Size		50R0 - 50Ω	1002 - 10KΩ	F - 1%	99 - 0.040" BeO		Blank - Bulk			
0805	1000 - 100Ω	1003 - 100KΩ	G - 2%				WP - Waffle Pack			
	1001 - 1KΩ	1004 - 1MΩ	J - 5%					TR - Tape & Reel		

Terminal Metallization

	RoHS	Magnetic	Solder	Epoxy	Wirebond
AS - Tin Lead over Platinum Palladium Gold	No	No	Yes	No	No
CB - Tin Lead over Nickel over Silver	No	Yes	Yes	No	No
CC - 100% Matte Tin over Copper over Silver	Yes	No	Yes	No	No
CT - 100% Matte Tin over Nickel over Silver	Yes	Yes	Yes	No	No
HA - Gold over Platinum Gold I/O Terminals w/ Platinum Palladium Gold Backplane	Yes	No	Yes (Backplane)	Yes	Yes (I/O Terminals)
JA - Gold over Platinum Palladium Gold	Yes	No	No	Yes	Yes

Barry Industries reserves the right to change part number and/or process without notification.

RM0805ZZ-XXXXWN-99 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65 to +125 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

Barry Industries reserves the right to change part number and/or process without notification.